

## 1 KEY TOUCH PAD DETECTOR IC

### GENERAL DESCRIPTION

The TTP223N-DO8 TonTouch™ is a touch pad detector IC which offers 1 touch key. The touching detection IC is designed for replacing traditional direct button key with diverse pad size. Low power consumption and wide operating voltage are the contact key features for DC or AC application.

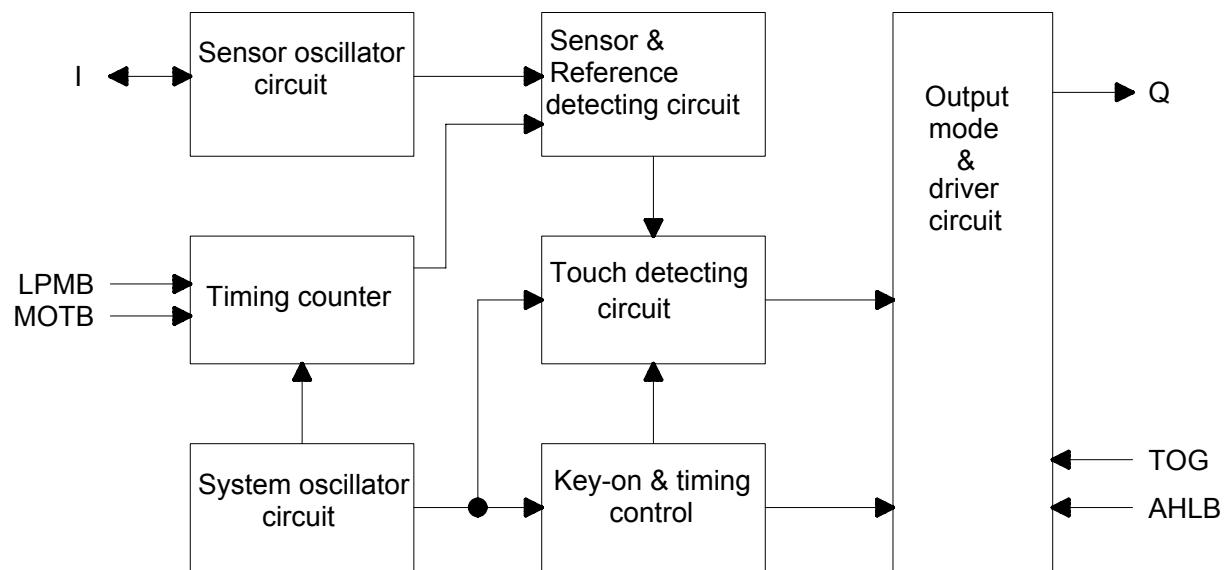
### FEATURES

- Operating voltage 2.0V~5.5V
- Operating current @VDD=3V, no load  
At low power mode typical 1.5uA, maximum 3.0uA  
At fast mode typical 3.5uA, maximum 7.0uA  
The response time max about 60mS at fast mode, 220mS at low power mode @VDD=3V
- Sensitivity can adjust by the capacitance(1~50pF) outside
- Stable touching detection of human body for replacing traditional direct switch key
- Provides Fast mode and Low Power mode selection by pad option(LPMB pin)
- Provides direct mode、toggle mode by pad option(TOG pin)  
Q pin is CMOS output
- All output modes can be selected active high or active low by pad option(AHLB pin)
- Have the maximum on time 100sec by pad option(MOTB pin)
- After power-on have about 0.5sec stable-time, during the time do not touch the key pad,  
And the function is disabled
- Auto calibration for life  
And the re-calibration period is about 4.0sec, when key has not be touched at fast mode.  
At low power mode the re-calibration period is the same 4.0sec normally,  
When key detected touch and released touch, the auto re-calibration will be redoing after  
about 16sec from releasing key

### APPLICATION

- Wide consumer products
- Button key replacement

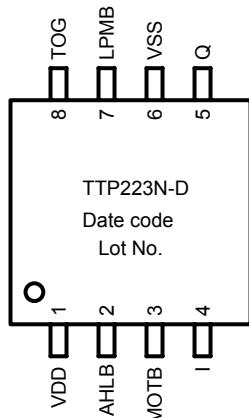
## BLOCK DIAGRAM



**PACKAGE LIST**

Package Type SOP-8

TTP223N-DO8 PACKAGE CONFIGURATION

**TTP223N-DO8**

**PAD DESCRIPTION**

Pad No.	Pad Name	I/O Type	Pad Description
1	VDD	P	Positive power supply
2	AHLB	I-PL	Output active high or low selection, 1=>Active low; 0(Default)=>Active high
3	MOTB	I-PH	Maximum on time 100sec selection, 1(Default)=>Disable, 0=>Enable
4	I	I/O	Input sensor port
5	Q	O	CMOS output pin
6	VSS	P	Negative power supply, ground
7	LPMB	I-PH	Low power mode selection, 1(Default)=>Fast mode; 0=>Low power mode
8	TOG	I-PL	Output type option pin, 1=>Toggle mode; 0(Default)=>Direct mode

**Pin Type**

I	CMOS input only
O	CMOS push-pull output
I/O	CMOS I/O
I-PH	CMOS input and pull-high resister
I-PL	CMOS input and pull-low resister
P	Power / Ground

**ELECTRICAL CHARACTERISTICS**
**• Absolute Maximum Ratings**

Parameter	Symbol	Conditions	Value	Unit
Operating Temperature	T <sub>OP</sub>	—	-20 ~ +70	°C
Storage Temperature	T <sub>STG</sub>	—	-50 ~ +125	°C
Power Supply Voltage	VDD	T <sub>a</sub> =25°C	VSS-0.3 ~ VSS+5.5	V
Input Voltage	V <sub>IN</sub>	T <sub>a</sub> =25°C	VSS-0.3 ~ VDD+0.3	V
Human Body Mode	ESD	—	4	kV
Note : VSS symbolizes for system ground				

**• DC/AC Characteristics : (Test condition at room temperature=25°C )**

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Operating Voltage	VDD		2.0	3	5.5	V
System oscillator	F <sub>FAST</sub>	VDD=3V	-	512K	-	Hz
	F <sub>LOW</sub>			16K		
Sensor oscillator	F <sub>SEN</sub>	VDD=3V no load	-	1M	-	Hz
Operating Current	I <sub>OP</sub>	VDD=3V at low power mode and output no load	-	1.5	3.0	uA
		VDD=3V at fast mode and output no load	-	3.5	7.0	
Input Ports	V <sub>IL</sub>	Input Low Voltage	0	-	0.2	VDD
Input Ports	V <sub>IH</sub>	Input High Voltage	0.8	-	1.0	VDD
Output Port Sink Current	I <sub>OL</sub>	VDD=3V, V <sub>OL</sub> =0.6V	-	8	-	mA
Output Port Source Current	I <sub>OH</sub>	VDD=3V, V <sub>OH</sub> =2.4V	-	-4	-	mA
Output Response Time	T <sub>R</sub>	VDD=3V, At fast mode			60	mS
		VDD=3V, At low power mode			220	
Input Pin Pull-high Resistor	R <sub>PH</sub>	VDD=3V, (LPMB, MOTB)		35K		ohm
Input Pin Pull-low Resistor	R <sub>PL</sub>	VDD=3V, (TOG, AHLB)		28K		ohm

## FUNCTION DESCRIPTION

### 1. Sensitivity adjustment

The total loading of electrode size and capacitance of connecting line on PCB can affect the sensitivity. So the sensitivity adjustment must according to the practical application on PCB. The TTP223N-DO8 offers some methods for adjusting the sensitivity outside.

1-1 by the electrode size

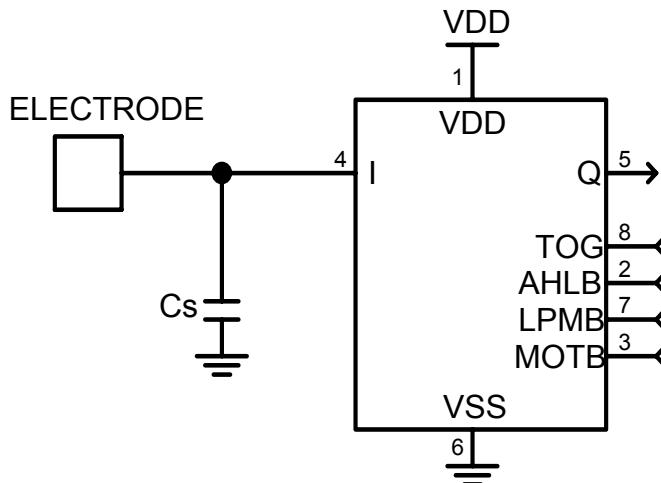
Under other conditions are fixed. Using a larger electrode size can increase sensitivity. Otherwise it can decrease sensitivity. But the electrode size must use in the effective scope.

1-2 by the panel thickness

Under other conditions are fixed. Using a thinner panel can increase sensitivity. Otherwise it can decrease sensitivity. But the panel thickness must be below the maximum value.

1-3 by the value of  $C_s$  (please see the down figure)

Under other conditions are fixed. When do not use the  $C_s$  to VSS, the sensitivity is most sensitive. When adding the values of  $C_s$  will reduce sensitivity in the useful range ( $1 \leq C_s \leq 50\text{pF}$ ).



### 2. Output mode

The TTP223N-DO8 has direct mode active high or low by AHLB pad option. And has toggle mode by TOG pad option. Pad Q is CMOS output.

TOG	AHLB	Pad Q option features
0	0	Direct mode, CMOS active high output
0	1	Direct mode, CMOS active low output
1	0	Toggle mode, Power on state=0
1	1	Toggle mode, Power on state=1

### 3. Maximum key on duration time (By MOTB pad option)

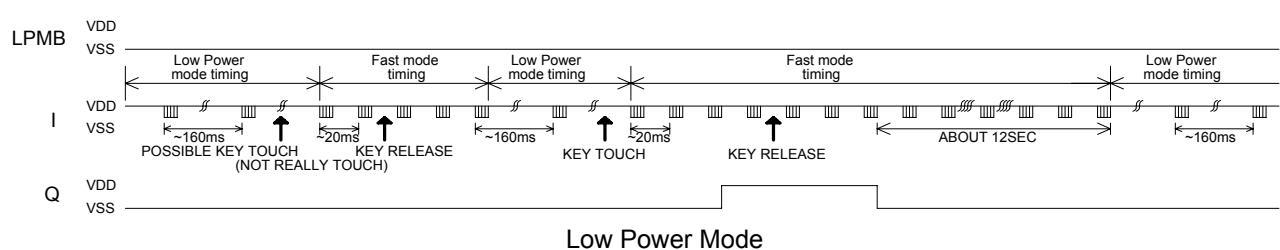
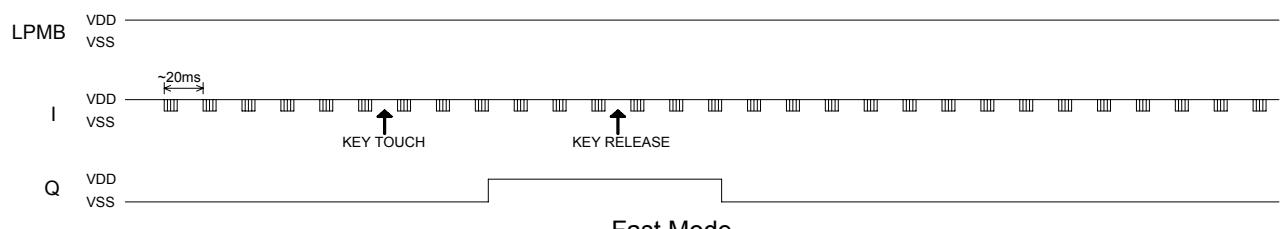
If some objects cover in the sense pad, and causing the change quantity enough to be detected. To prevent this, the TTP223N-DO8 sets a timer to monitor the detection. The timer is the maximum on duration time. It is set about 100sec at 3V. When the detection is over the timer, the system will return to the power-on initial state, and the output becomes inactive until the next detection.

MOTB	Option features
1	Infinite(Disable maximum on time)
0	Maximum on time 100sec

### 4. Fast and Low power mode selection (By LPMB pad option)

The TTP223N-DO8 has Fast mode and Low Power mode to be selected. It depends on the state of LPMB pin. When the LPMB pin is opened or connected to VDD, the TTP223N-DO8 runs in Fast mode. When the LPMB pin is connected to VSS, the TTP223N-DO8 runs in Low Power mode. In the Fast mode response time is faster, but the current consumption will be increased. In the Low Power mode it will be saving power, but will be slowing response time for first touch. When it awaked in fast mode, the response time is the same the fast mode. In this mode when detecting key touch, it will switch to Fast mode. Until the key touch is released and will keep a time about 12sec. Then it returns to Low Power mode.

The states and timing of two modes please see below figure.

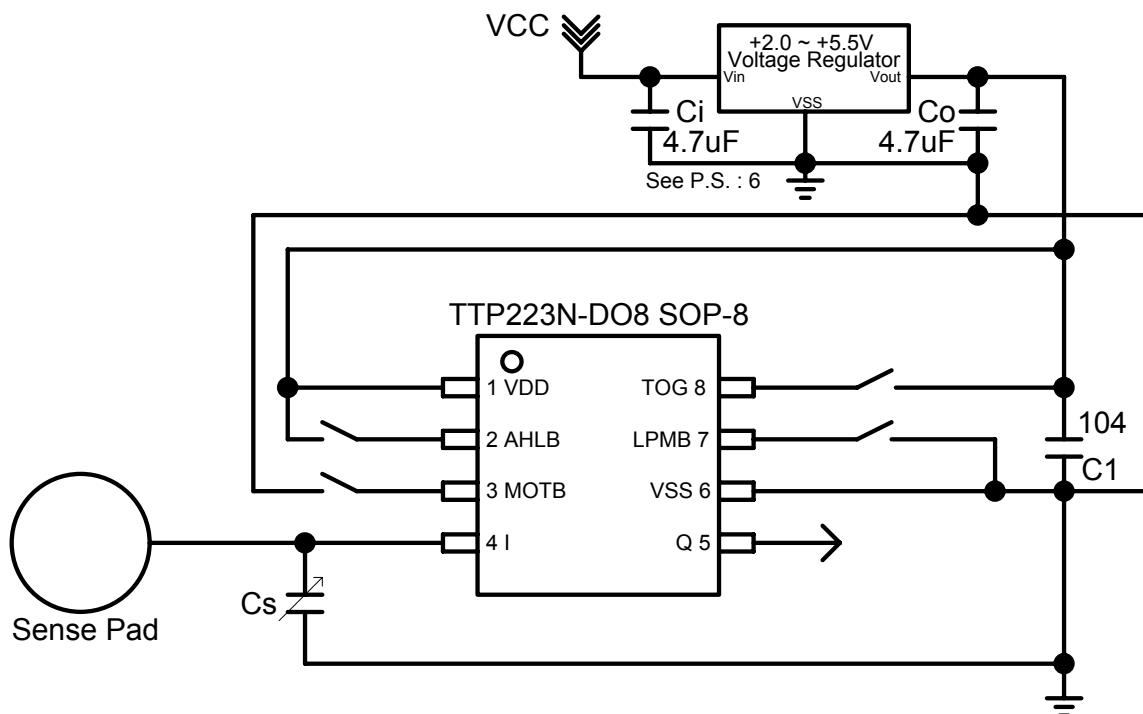


LPMB	Option features
1	Fast mode
0	Low Power mode

### 5. Option pin

For power saving concern and package bonding option consideration, all the feature option pins with latch type design and initial states are 0 or 1 as power on. If those pins are forced to VDD or VSS, the states will be changed to 1 or 0 without any current leakage to conflict the power saving issue.

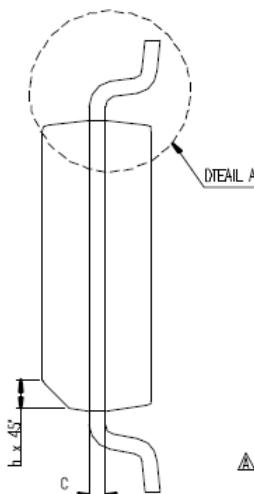
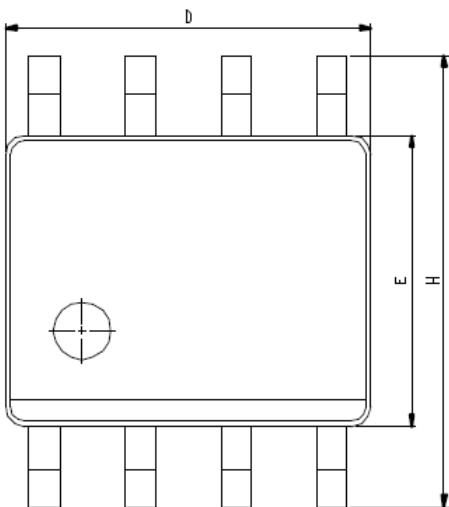
Feature option pins	Initial state by Power on
AHLB	0
TOG	0
LPMB	1
MOTB	1

**APPLICATION CIRCUIT**


- PS : 1. On PCB, the length of lines from touch pad to IC pin shorter is better.  
     And the lines do not parallel and cross with other lines.
2. The power supply must be stable. If the supply voltage drift or shift quickly, maybe causing sensitivity anomalies or false detections.
3. The material of panel covering on the PCB can not include the metal or the electric element. The paints on the surfaces are the same.
4. The capacitance Cs can be used to adjust the sensitivity. The value of Cs use smaller, then the sensitivity will be better. The sensitivity adjustment must according to the practical application on PCB. The range of Cs value is 1~50pF.
5. The C1 capacitor must be used between VDD and VSS; and should be routed with very short tracks to the device's VDD and VSS pins (TTP223N-DO8).
6. The value of capacitors can be used by the real application for Ci and Co capacitors.
7. The sensitivity adjustment capacitors (Cs) must use smaller temperature coefficient and more stable capacitors. Such are X7R, NPO for example. So for touch application, recommend to use NPO capacitor, for reducing that the temperature varies to affect sensitivity.

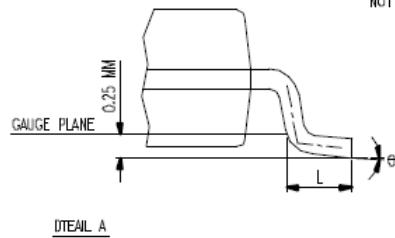
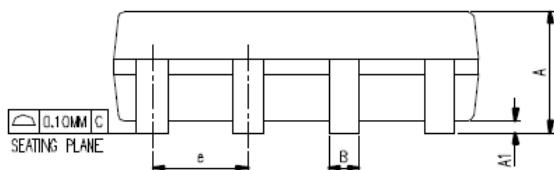
Package Type: SOP-8

## Package Outline Dimension



SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN.	MAX
A	1.35	1.75	0.0532	0.0688
A1	0.10	0.25	0.0040	0.0098
B	0.33	0.51	0.013	0.020
C	0.19	0.25	0.0075	0.0098
e	1.27	BSC	0.050	BSC
D	4.80	5.00	0.1890	0.1988
H	5.80	6.20	0.2284	0.2440
E	3.80	4.00	0.1497	0.1574
L	0.40	1.27	0.016	0.050
h	0.25	0.50	0.0099	0.0196
θ	0°	8°	0°	8°
JEDEC	MS-012 (AA)			

▲NOTES : DIMENSION "D" DOES NOT INCLUDE MOLD FLASH ,  
PROTRUSIONS OR GATE BURRS.  
MOLD FLASH , PROTRUSIONS AND GATE BURRS SHALL  
NOT EXCEED 0.15 MM ( 0.006 INCH ) PER SIDE



**Ordering Information****TTP223N-DO8**

Package Type	Chip Type	Wafer Type
TTP223N-DO8	No support	No support

**REVISE HISTORY**

1. 2016/6/15  
-Original version : V\_1.0